

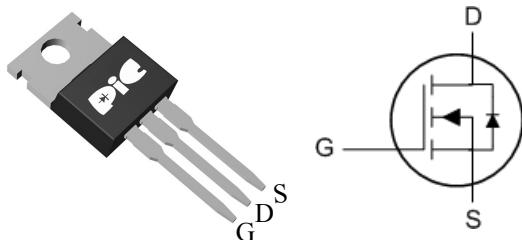
➤ General Description

This PAN00TG14G N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➤ Feature

- Super Low Gate Charge
- 100% EAS Guaranteed
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology
- TO-220 package design

➤ TO-220



➤ Application

- SMPS Power Supplier.
- Charger Adapter
- Power Tools
- LED Lighting

➤ Absolute Maximum Ratings

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V _{DS}	100	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current, V _{GS} @ 10V ¹	I _D @T _C =25°C	11.8	A
Continuous Drain Current, V _{GS} @ 10V ¹	I _D @T _C =100°C	7.4	A
Pulsed Drain Current ²	I _{DM}	24	A
Total Power Dissipation ³	P _D @T _C =25°C	52.1	W
Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 150	°C
Thermal Resistance Junction-ambient ¹	R _{θJA}	62	°C/W
Thermal Resistance Junction-Case ¹	R _{θJC}	2.4	°C/W

➤ Electrical Characteristics (T_J=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	100	---	---	V
BVDSS Temperature Coefficient	△BV _{DSS} /△T _J	Reference to 25°C, I _D =1mA	---	0.122	---	V/°C
Static Drain-Source On-Resistance ²	R _{DS(ON)}	V _{GS} =10V, I _D =8A	---	---	152	mΩ
		V _{GS} =4.5V, I _D =6A	---	---	158	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	1.0	---	2.5	V
V _{GS(th)} Temperature Coefficient	△V _{GS(th)}		---	-4.84	---	mV/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =80V, V _{GS} =0V, T _J =25°C	---	---	10	uA
		V _{DS} =80V, V _{GS} =0V, T _J =55°C	---	---	100	
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Forward Transconductance	g _f s	V _{DS} =5V, I _D =8A	---	10.2	---	S
Gate Resistance	R _g	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	2.3	---	Ω
Total Gate Charge (10V)	Q _g	V _{DS} =60V, V _{GS} =10V, I _D =8A	---	25.5	---	nC
Gate-Source Charge	Q _{gs}		---	4.2	---	
Gate-Drain Charge	Q _{gd}		---	4.3	---	
Turn-On Delay Time	T _{d(on)}	V _{DD} =50V, V _{GS} =10V, R _G =3.3Ω	---	17.3	---	ns
Rise Time	T _r		---	2.8	---	
Turn-Off Delay Time	T _{d(off)}		---	50	---	
Fall Time	T _f		---	2.8	---	
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	1077	---	pF
Output Capacitance	C _{oss}		---	46	---	
Reverse Transfer Capacitance	C _{rss}		---	32	---	

➤ Diode Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Continuous Source Current ^{1,4}	I _s	V _G =V _D =0V, Force Current	---	---	11.8	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _s =1A, T _J =25°C	---	---	1.2	V
Reverse Recovery Time	t _{rr}	I _F =8A, dI/dt=100A/μs, T _J =25°C	---	30	---	nS
Reverse Recovery Charge	Q _{rr}		---	16	---	nC

Note :

- 1.Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.Ensure that the channel temperature does not exceed 150°C.
- 4.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

➤ Typical Characteristics

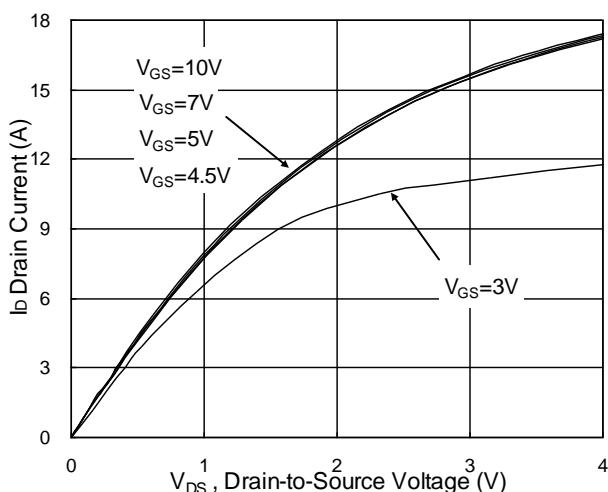


Fig.1 Typical Output Characteristics

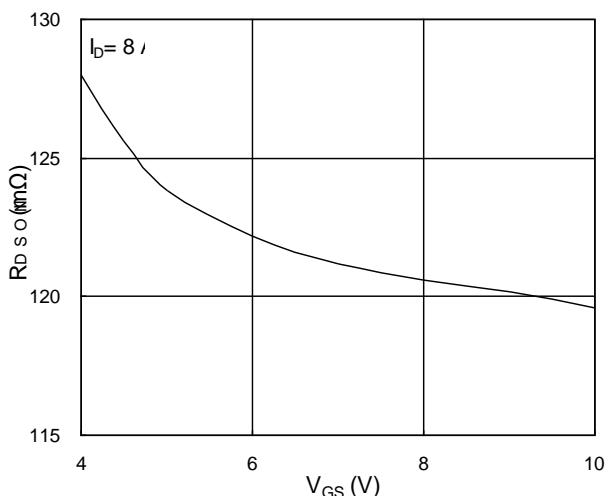


Fig.2 On-Resistance vs. Gate-Source

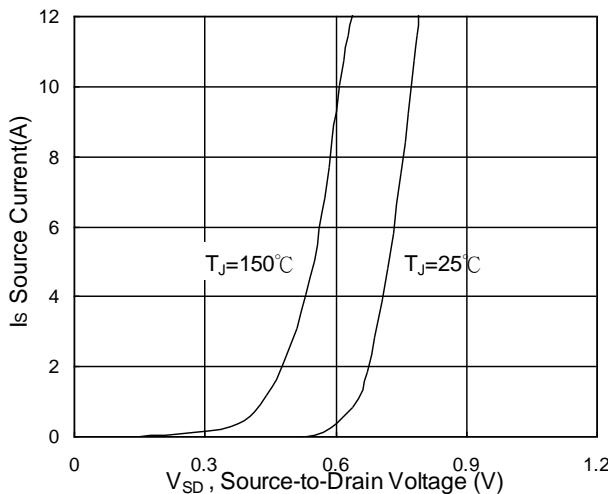


Fig.3 Forward Characteristics Of Reverse

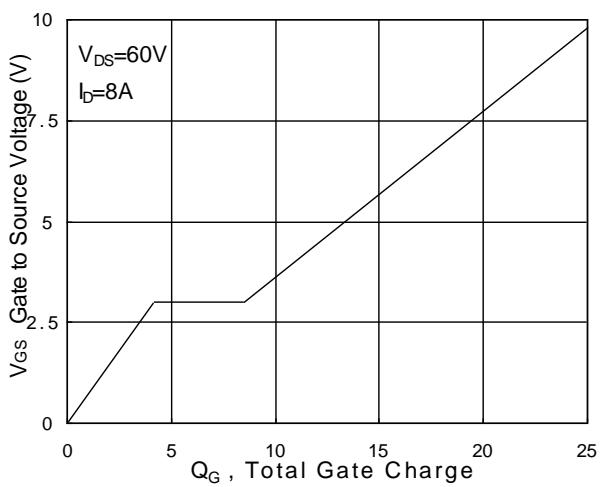


Fig.4 Gate-Charge Characteristics

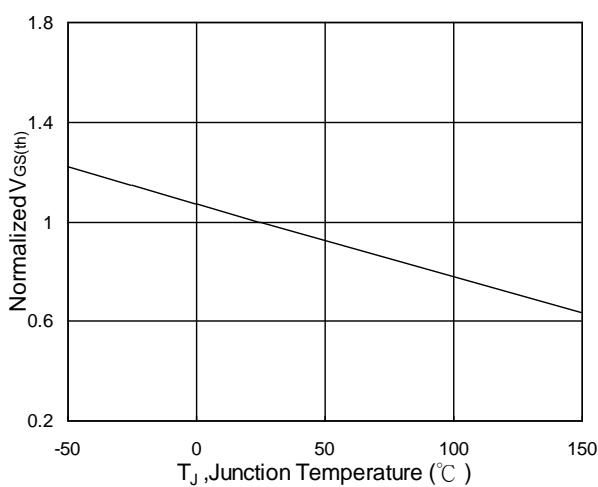


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

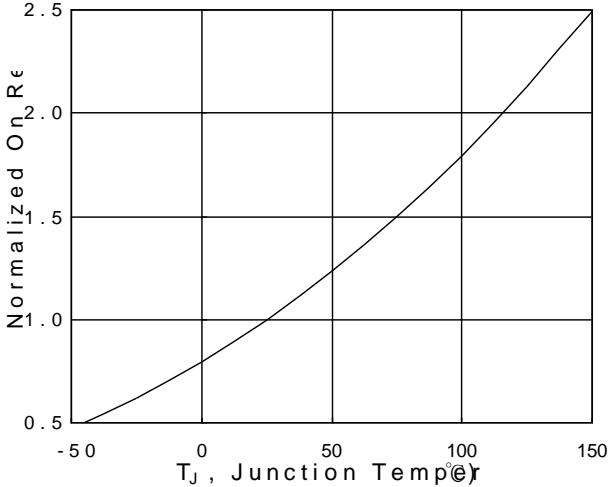
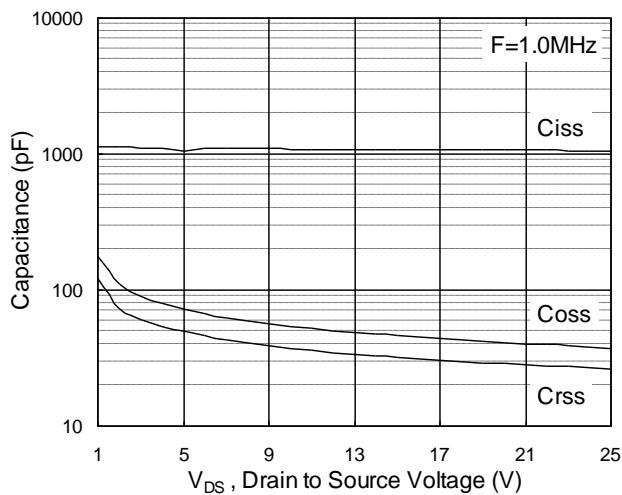
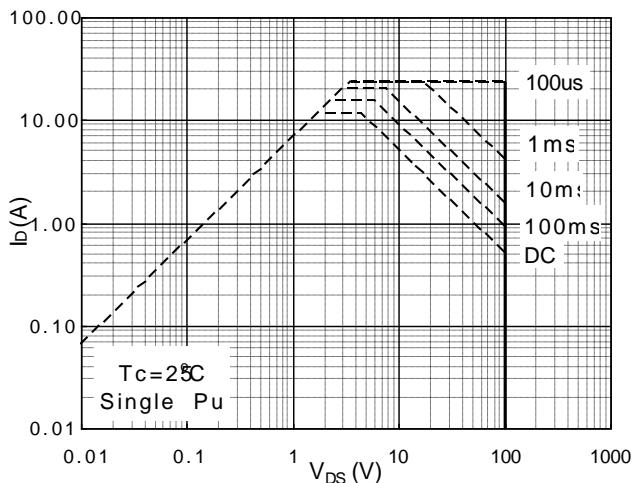
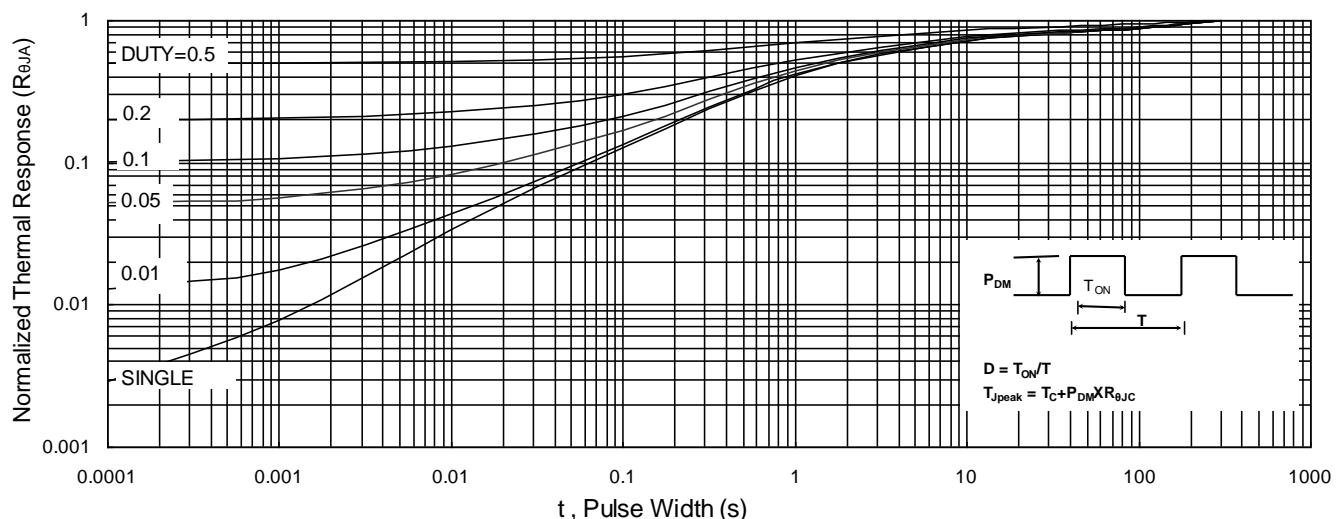
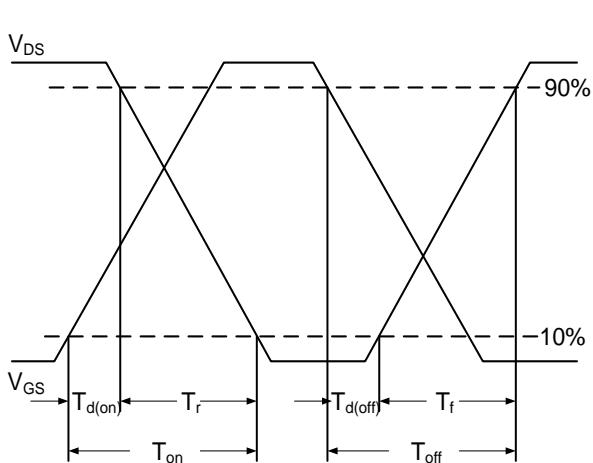
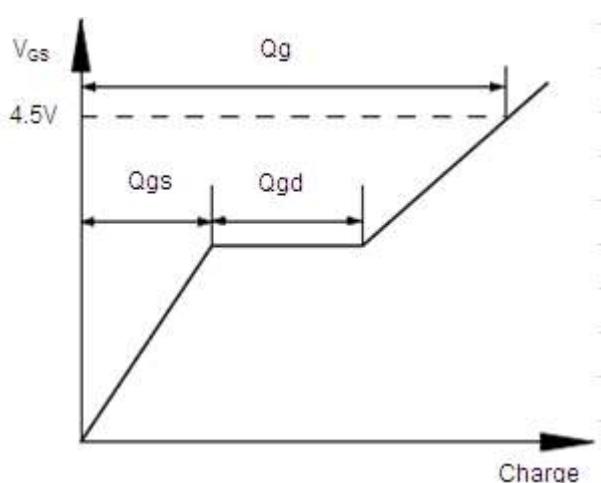
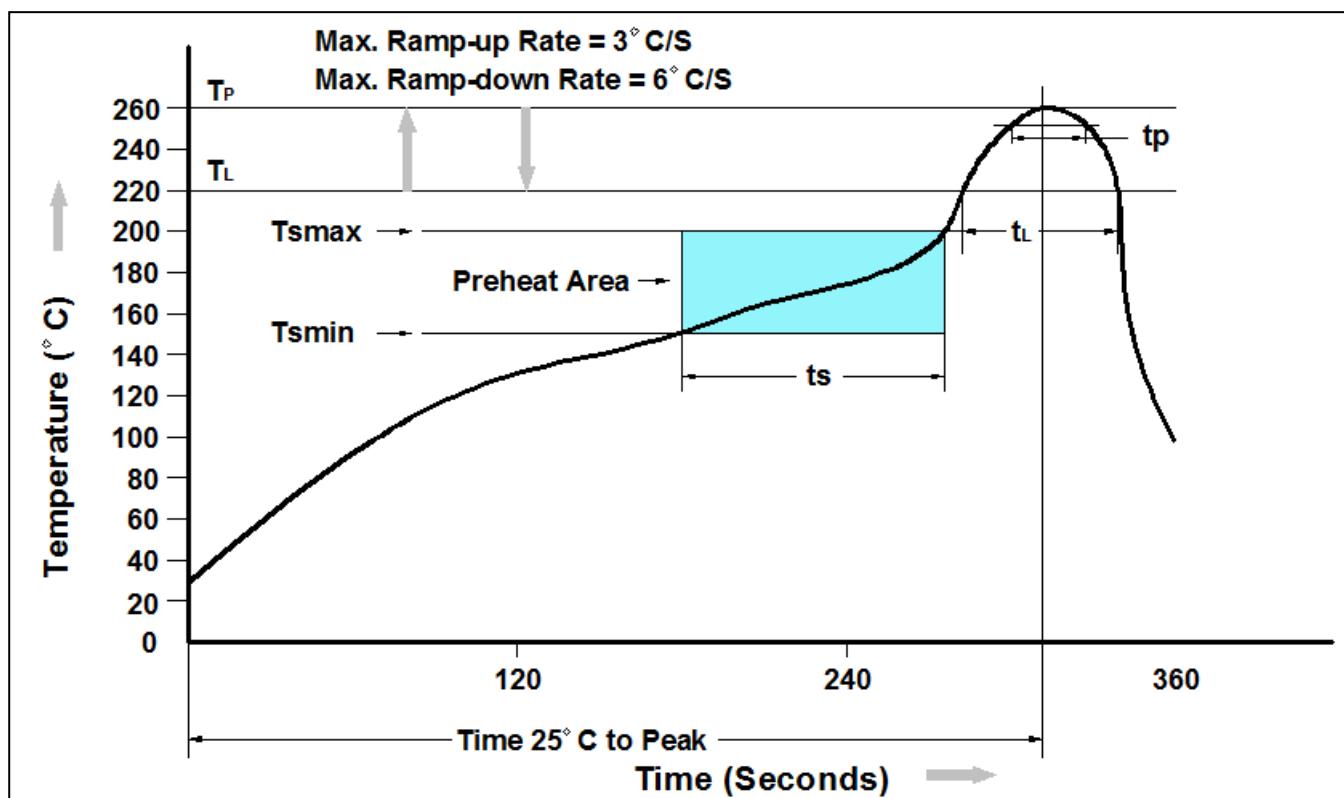


Fig.6 Normalized $R_{DS(on)}$ vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Gate Charge Waveform

➤ Recommand IR Reflow Soldering Thermal Profile

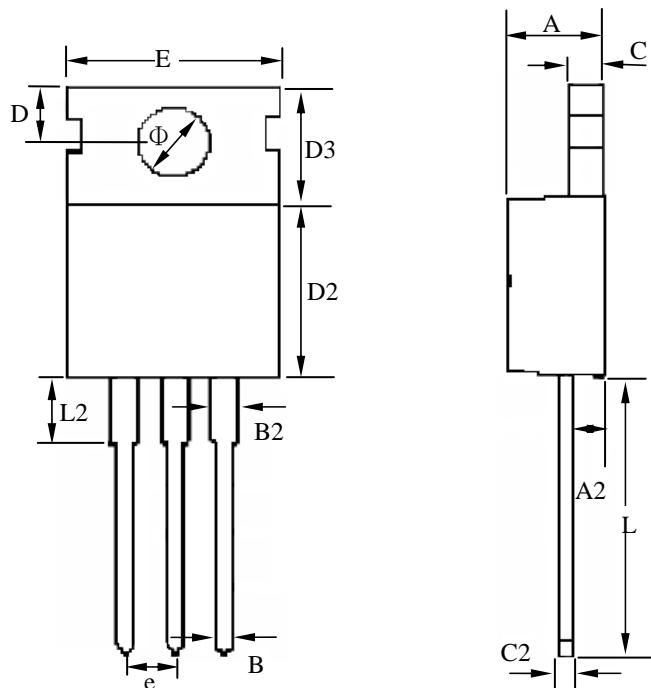


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	150°C
Temperature Max. (T _{smax})	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds
Average Ramp-up Rate (t _L to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➤ Ordering Information

Part Number	Description	Quantity
PAN00TG14G	TO-220	50 pcs/tube

➤ Package Information (TO-220)



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.25	--	4.80	0.167	--	0.189
A2	2.20	--	2.92	0.087	--	0.115
B	0.70	--	0.91	0.028	--	0.036
B2	1.15	--	1.77	0.045	--	0.070
C	1.20	--	1.40	0.047	--	0.055
C2	0.45	--	0.61	0.018	--	0.024
D	2.54	--	3.00	0.100	--	0.118
D2	8.39	--	9.47	0.330	--	0.373
D3	6.30	--	6.70	0.248	--	0.264
E	9.70	--	10.36	0.382	--	0.408
L	12.75	--	14.40	0.502	--	0.567
L2	2.45	--	4.05	0.096	--	0.159
Φ	3.50	--	3.80	0.138	--	0.150
e	--	2.54	--	--	0.100	--

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